Overall Board Thickness: 62 Mil
Soldermask Color: Black
Drill hole tolerance: +/-3 Mil
Copper/Spacing Clearances: 6/6 Mil
Finish: Immersion Gold

<table>
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<tr>
<th>SIZE</th>
<th>QTY</th>
<th>SYM</th>
<th>PLATED</th>
<th>TOL</th>
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<td>+</td>
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<tr>
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<td>X</td>
<td>NO</td>
<td>+/-0.0</td>
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TOP: 1 OZ
10 MIL FR4
INTERNAL: 1 OZ
40 MIL FR4
INTERNAL: 1 OZ
10 MIL FR4
BOTTOM: 1 OZ
62 MIL
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